MLS-DBC

Introduction

MLS-DBC is designed specifically for embedded passives or buried capacitance constructions. The uniform, ultra low profile of the primary bonding surface provides a minimum of surface penetration and a maximum of dielectric spacing enhancing electrical performance.

Benefits

- Uniform, ultra low profile bonding surface
- Less prone to resist lock-in
- Compatible with ammoniacal etchants

Typical Physical Characteristics

Oak-Mitsui foils meet all requirements of IPC-4562

Nominal Thickness		microns	18	35	70
Area Weight		oz/ft²	1/2	1	2
Tensile	ambient	Kpsi	60	55	52.5
	180°C	Kpsi	30	30	30
Elongation	ambient	%E	8	15	20
	180°C	%E	8	8	8
Roughness	drum	Ra	115	115	115
	matte	Rmax	175	250	400
Peel Strength B Epoxy, Tg 170°C	drum	lbs/in	6	8	8.5
	matte	lbs/in	5.5	6	7

The information contained in this specification is not intended to and does not create any warranties, express or implied, including any warranty of merchantability or fitness for a particular purpose. The actual performance of Mitsui materials will vary according to the customer's application.